

Alloy Designation	
EN	Cu-DHP / CW024A
DIN	SF-Cu / 2.0090 DIN EN1652
UNS	C12200 ASTM B152
JIS	C1220

Chemical Composition		
Cu	min. 99.9	%
O	0.015 - 0.04	%

Characteristics
Cu-DHP is a phosphorus-deoxidized copper (about 99.9% Cu, 0.02% P) engineered for severe forming and deep-drawing operations. It offers superior ductility versus Cu-ETP and excellent hot/cold formability, The phosphorus deoxidation eliminates hydrogen-embrittlement risk during brazing, welding or annealing, and gives reliably good soldering/welding performance. Electrical and thermal conductivity are slightly lower than Cu-ETP.

Main Applications
Pipe caps brazed heat exchangers heating elements
Wire connectors Oil Coolers in Airplanes Plating Anodes
Strips for welded tube cladding of steel and stainless steel
Deep drawn copper items Casting Molds Marine Oil Coolers

Physical Properties (Reference values at room temperature)		
Density	g/cm ³	8.94
Electrical conductivity	IACS%(20°C)*	80
Modulus of elasticity	KN/mm ²	115
Coefficient of thermal expansion	10 ⁻⁶ /K	17.7
Thermal conductivity	W/(m*K)	335

*value for the lowest temper class

Mechanical Properties							
TEMPER		Tensile Strength Mpa	Yield Strength Mpa	Elongation %	Hardness Hv	Bending Test(90°) GW BW	
R220	H00	220 - 275	max. 140	min. 33	40 - 70	0	0
R240	H01	235 - 300	min. 180	min. 8	65 - 95	0	0
R290	H04	290 - 360	min. 250	min. 4	90 - 110	0	0
R360	H10	min. 360	min. 320	min. 2	min. 110	0	0.5

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